

LTM8027 113LD -BGA-15mm X 15mm X 4.92mm - SOLDER DA(TABLE OF MATERIAL DECLARATION)

This package is RoHS compliant per EU RoHS Directive 2003/95/EC. It contains less than 100ppm cadmium (Cd)and less than 1,000ppm of each - lead (Pb), mercury (Hg),hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)

No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)
1	Substrate	Circuit Board	0.2089	Barium Compounds	7727-43-7	0.00251	1.20
				Filler Substances (Silica Crystalline)	13776-74-4, 7631-86-9	0.03249	15.55
				Copper Metal	7440-50-8	0.13500	64.62
				Copper Compounds	1328-53-6	0.00004	0.02
				Ecotoxic substances	7440-38-2, 7440-28-0	0.00003	0.01
				Gold metal or alloy	7440-57-5	0.00100	0.48
				Nickel	7440-02-0	0.00466	2.23
				Zinc	7440-66-6	0.00031	0.15
				Bismaleimide/Triazine Resin	105391-33-1/25722-66-1	0.02553	12.22
				Acrylic Resin	non-disclosure	0.00543	2.60
				Epoxy Resin	non-disclosure	0.00002	0.01
				Chromium(III) Oxide	1308-38-9	0.00001	0.00
				Silica crytalline	14808-60-7	0.00065	0.31
				Silica amorphous	7631-86-9	0.00003	0.01
				Talc;not containing fibers like asbestos	14807-96-9	0.00033	0.16
				Aromatic Carbonyl compounds	non-disclosure	0.00056	0.27
				Cyanoguanidine	461-58-5	0.00001	0.01
				Calcium caobonate	471-34-1	0.00000	0.00
				Amine compounds	non-disclosure	0.00009	0.04
				Leveling agent and others	non-disclosure	0.00021	0.10
2	Solder Paste	Alloy	0.1679	Sn	7440-31-5	0.15951	95.00
				Sb	7440-36-0	0.00840	5.00
3	Epoxy		0.0007	Di-ester resin	non-disclosure	0.00006	8.00
				Functionalized ester	non-disclosure	0.00006	8.00
				Silver	7440-22-4	0.00059	84.00
4	Passive/Active Components		0.5324	Iron Powder (Fe)	7430-89-6	0.36800	69.12
				Copper (Cu)	7440-50-8	0.10370	19.48
				Nickel (Ni)	7440-02-0	0.00530	1.00
				Tin (Sn)	7440-31-5	0.00450	0.85
				Ceramic (Ba) compund	12047-27-7	0.05010	9.41
				Glass	60676-86-0	0.00050	0.09
				Epoxy Resin	non-disclosure	0.00030	0.06
5	Active Ics	Silicon	0.0153	Silicon	7440-21-3	0.01530	100.00
5	solder ball		0.1911	Sn	7440-31-5	0.18441	96.50
				Ag	7440-22-4	0.00573	3.00
				Cu	7440-50-8	0.00096	0.50
6	Wire	Gold	0.0018	Au	7440-57-5	0.00180	99.99
7	Encapsulation	Epoxy Resin	1.6759	Fused Silica	60676-86-0	1.29378	77.20
				Epoxy Resin	non-disclosure	0.14915	8.90
				Phenol Resin	non-disclosure	0.14915	8.90
				Crytalline Silica	14808-60-7	0.05028	3.00
				Carbon Black	1333-86-4	0.00838	0.50
				Metal Hydroxide	non-disclosure	0.02514	1.50
Total Package Weight			2.7940				

Note: Composition derived from MSDS and material C of C from Vendors
Component Weight based on assembly of generic parts